

## 2A, 200V-1000V Surface Mount Rectifiers

#### **FEATURES**

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- · Freewheeling application
- Switching mode converters and inverters, computer and telecommunication.

#### **MECHANICAL DATA**

- · Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Pure tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.029 g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
l <sub>F</sub>	2	Α	
$V_{RRM}$	200-1000	٧	
I <sub>FSM</sub>	50	Α	
T <sub>J MAX</sub>	150	°C	
Package	Thin SMA		
Configuration	Single Die		





Thin SMA

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	S2DAL	S2GAL	S2JAL	S2KAL	S2MAL	UNIT
Marking code on the devi	ce		S2DAL	S2GAL	S2JAL	S2KAL	S2MAL	
Repetitive peak reverse v	oltage	$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms	s value	$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I <sub>F</sub>			2			Α
Surge peak forward current, single half sine-	8.3ms at T <sub>A</sub> = 25°C	1			50			А
wave superimposed on rated load per diode	1.0ms at T <sub>A</sub> = 25°C	IFSM			140			А
Junction temperature		$T_J$	-55 to +150		°C			
Storage temperature		T <sub>STG</sub>	-55 to +150		°C			

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	R <sub>OJL</sub>	14	°C/W	
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	74	°C/W	
Junction-to-case thermal resistance	R <sub>eJC</sub>	20	°C/W	

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage (1)	$I_F = 1.0A, T_J = 25^{\circ}C$	V <sub>F</sub>	0.91	-	V
	$I_F = 2.0A, T_J = 25^{\circ}C$		0.98	1.10	V
	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.79	-	V
	I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C		0.88	0.98	V
Reverse current @ rated V <sub>R</sub> (2)	T <sub>J</sub> = 25°C	I <sub>R</sub>	-	1	μA
	T <sub>J</sub> = 125°C		-	33	μA
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	12	-	pF

#### Notes:

- (1) Pulse test with PW=0.3 ms
- (2) Pulse test with PW=30 ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
S2xAL M3G	Thin SMA	3,500 / 7" reel	
S2xAL M2G	Thin SMA	14,000 / 13" reel	

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## Notes:

(1) "x" defines voltage from 200V(S2DAL) to 1000V(S2MAL)



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

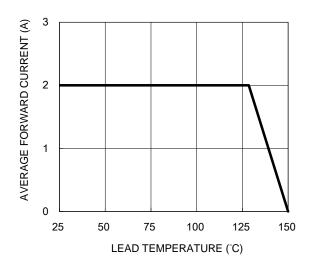


Fig.3 Typical Reverse Characteristics

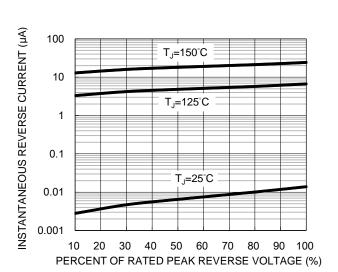


Fig.2 Typical Junction Capacitance

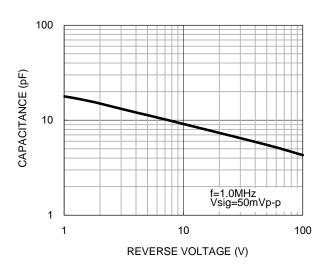


Fig.4 Typical Forward Characteristics

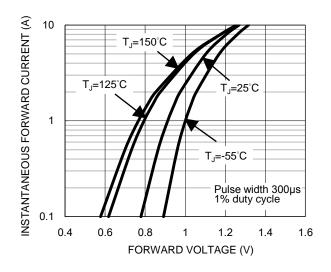
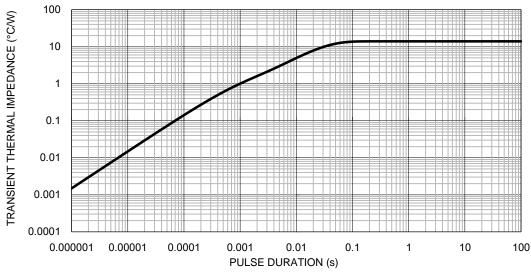


Fig.5 Typical Transient Thermal Impedance

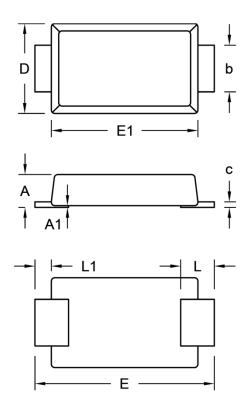


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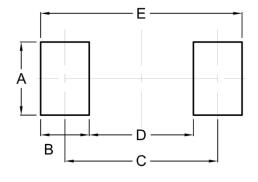
## **PACKAGE OUTLINE DIMENSIONS**

Thin SMA



DIM	DIM. Unit (mm) Min. Max.		Unit (	(inch)	
DIIVI.			Min.	Max.	
Α	0.90	1.00	0.035	0.039	
A1	0.00	0.10	0.000	0.004	
b	1.25	1.45	0.049	0.057	
С	0.10	0.22	0.004	0.009	
D	2.50	2.70	0.098	0.106	
E	5.05	5.35	0.199	0.211	
E1	4.15	4.35	0.163	0.171	
L	0.75	1.20	0.030	0.047	
L1	0.30	0.60	0.012	0.024	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

## **MARKING DIAGRAM**



P/N = Marking Code ΥW = Date Code F = Factory Code



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